

We thank you for your price request and are pleased to present you the following quotation today

26 June 2017

#### Administrative details

##### Your references

Offer nr.	B1101795	Purchase reference	-
Service	STANDARD pool	Project reference	-
Board name	N-DAP	Article number	-

##### Invoicing & delivery details

###### Invoice to:

Cork Institute of Technology  
Catherine Cunningham  
Rossa Avenue Bishopstown  
ACCOUNTS PAYABLE  
co Cork  
Ireland  
+353 (21) 4326584  
accountspayable@cit.ie

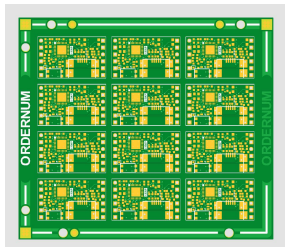
###### Delivered to:

Cork Institute of Technology, NIMBUS  
CENTRE  
Nikolaos Chalikias  
Rossa Avenue Bishopstown  
co Cork  
Ireland  
+353 (21) 4335479  
nikolaos.chalikias@cit.ie

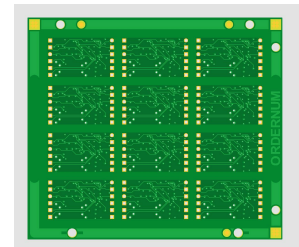
#### PCB Visualizer

##### PCB images

Top view :

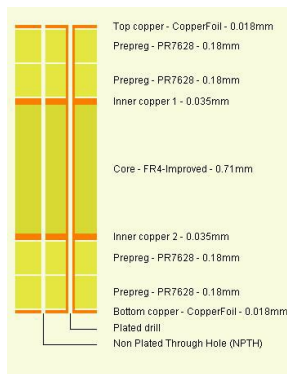


Bottom view:



##### Buildup & Mechanical plan

Board buildup :



#### Technology & options

##### Board definition

Number of layers	4	Delivery format	Eurocircuits, according to standard panel rules
PCB width (X)	25.40 mm	PCB height (Y)	15.50 mm
eC-registration compatible	Yes		

##### Panel definition

Repeat in X	3	Repeat in Y	4
Panel width	94.20 mm	Panel height	82 mm
PCBs per panel	12	Panel border	5 mm
PCB separation method	Breakrouting	PCB spacing	2 mm
Panel without cross outs	No	Panel outline	Routed

##### Board definition

Top soldermask	Green	Bottom soldermask	Green
Top legend	White	Bottom legend	White
Surface finish	Che Ni/Au selective		
Bare board testing	Yes		

##### Board technology

Pattern class	8	Drill class	Drill D
Outer layer trackwidth (OL-TW)	0.150 mm	Hole density	>2000/dm2
Outer layer isolation distance (OL-TT-TP-PP)	0.150 mm	Holes <= may be reduced	0.45 mm
Outer layer annular ring (OAR)	0.100 mm		
Inner layer trackwidth (IL-TW)	0.150 mm	Holes <= may be reduced	0.45 mm
Inner layer isolation distance (IL-TT-TP-PP)	0.150 mm		
Inner layer annular ring (IAR)	0.125 mm		

**Material definition**

Board thickness	1.55 mm	Board buildup	Standard buildup
Base material	FR4IMP	Material Tg	145-150°C
Outer layer copper foil	18µm(End-Cu +/-35µm)	Inner layer copper foil	35µm
Extra PTH runs	0	Extra press cycles	0
Reversed buildup	No	Inner layer core thickness	Standard

**Stencils**

Top stencil	Yes	Bottom stencil	No
Stencil width (X)	189.2 mm	Stencil width (X)	189.2 mm
Stencil height (Y)	122 mm	Stencil height (Y)	122 mm
eC-registration compatible	Yes		

**Advanced options**

Copper up to board edge	No	Plated holes on the board edge	No
Specific tolerances	No	Specific marking	No
Press-fit holes	No	Depth routing	No
Round-edge plating	No	Chamfered mechanical holes	No

**Pricing****Printed circuits**

Basket nr.	Delivery term	Quantity	Unit price	Transport price	Transport mode	Total price	VAT	Gross
B1101795	7 Working days	2	88.69 EUR	3.68 EUR	Express	181.06 EUR	0.0 %	181.06 EUR

**Stencils**

Basket nr.	Stencil type	Delivery term	Quantity	Unit price	Transport price	Transport mode	Total price	VAT	Gross
B1101795	Stencil-Top	7 Working days	1	28.41 EUR	0.00 EUR	Express	28.41 EUR	0.0 %	28.41 EUR

**Payment terms & conditions**

The payment term is 30 days from invoice date.

This quotation is valid for 30 days. All our deliveries are according to our general terms and conditions of delivery. These are available on the website , and agreed upon between us during the registration procedure. All above mentioned prices are an indication on the basis of the information at our disposal on the moment of quotation. These prices may be reviewed at the moment of order on the basis of the final documentation and conditions. The final quantity to be delivered can vary up to 5% of the ordered quantity. Delivery terms start counting upon receipt of the complete documentation and firm order.

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